

## SSC8L62GN6

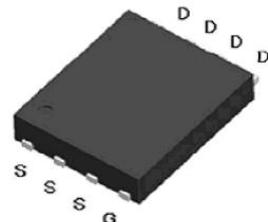
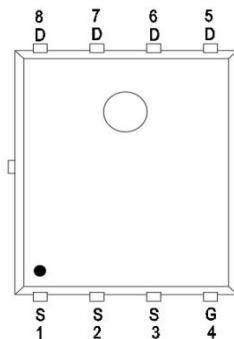
### N-Channel Enhanced MOSFET

#### ➤ Features

VDS	VGS	RDS(on) Typ.	ID
60V	±20V	8mR@10V	60A
		12mR@4V5	

#### ➤ Pin configuration

Top view



PDFN5X6

#### ➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDS(on) with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

**100% UIS Tested.**

#### ➤ Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

#### ➤ Ordering Information

Device	Package	Shipping
SSC8L62GN6	PDFN5X6	5000/Reel



Marking

(XX: product year / YY: product week)

➤ **Absolute Maximum Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	60	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>d</sup>	$T_C=25^\circ\text{C}$	60
		$T_C=100^\circ\text{C}$	31
$I_{DSM}$	Continuous Drain Current <sup>a</sup>	$T_A=25^\circ\text{C}$	19
		$T_A=70^\circ\text{C}$	14
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	240	A
$P_D$	Power Dissipation <sup>c</sup>	$T_C=25^\circ\text{C}$	46
		$T_C=100^\circ\text{C}$	18
$P_{DSM}$	Power Dissipation <sup>a</sup>	$T_A=25^\circ\text{C}$	5
		$T_A=70^\circ\text{C}$	3.2
$I_{AS}$	Avalanche Current <sup>b</sup> L=0.5mH Single Pulse	18	A
$E_{AS}$	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse	81	mJ
$T_J$	Operation junction temperature	-55~150	$^\circ\text{C}$
$T_{STG}$	Storage temperature range	-55~150	

➤ **Thermal Resistance Ratings( $T_A=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	25	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	2.7	

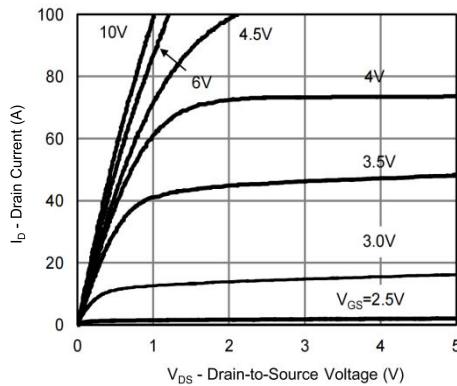
Note:

- a. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user specific board design. The power dissipation is based on the t  $\leq 10\text{s}$  thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

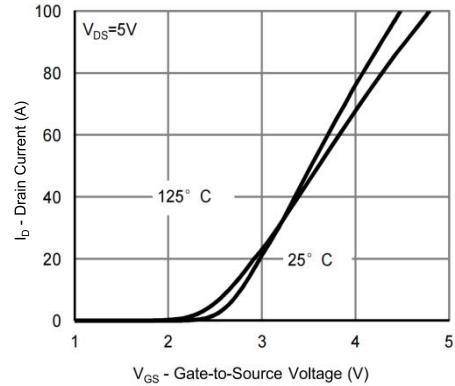
➤ Electronics Characteristics( $T_A=25^\circ C$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, ID=250\mu A$	60			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=250\mu A$	1.0	1.8	2.4	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=10V, ID=30A$		8	9.5	mR
	On-Resistance	$V_{GS}=4.5V, ID=20A$		12.5	15.5	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=5V, ID=20A$		30		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, IS=20A$		0.8	1.3	V
$R_g$	Gate Resistance	$V_{DS}=0V, f=1MHz$		1.4		R
$C_{iss}$	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1MHz$		960		pF
$C_{oss}$	Output Capacitance			380		
$C_{rss}$	Reverse Transfer Capacitance			22		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=10V, RL=1.5R$		5.4		ns
$Tr$	Rise time			18.3		
$T_{D(OFF)}$	Turn-off delay time			17.4		
$Tf$	Fall time			18.4		
$Q_G$	Total Gate Charge	$V_{GS}=10V, V_{DS}=30V, ID=20A$		16		nC
$Q_{GS}$	Gate Source Charge			4.4		
$Q_{GD}$	Gate Drain Charge			2.3		
$T_{rr}$	Diode Recovery Time	$IF=20A, di/dt=500A/us$		22		ns
$Q_{rr}$	Diode Recovery Charge	$IF=20A, di/dt=500A/us$		54		nC

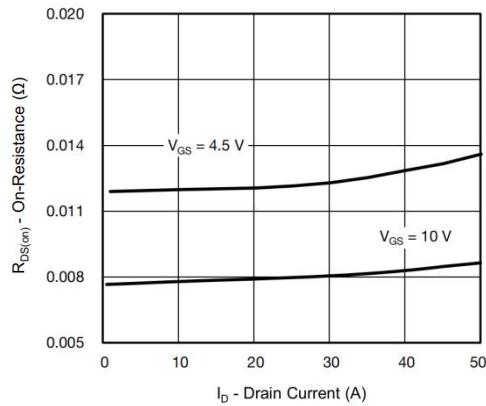
➤ **Typical Characteristics( $T_A=25^\circ\text{C}$  unless otherwise noted)**



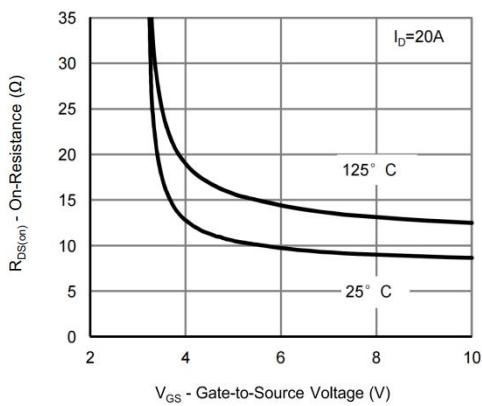
**Output Characteristics**



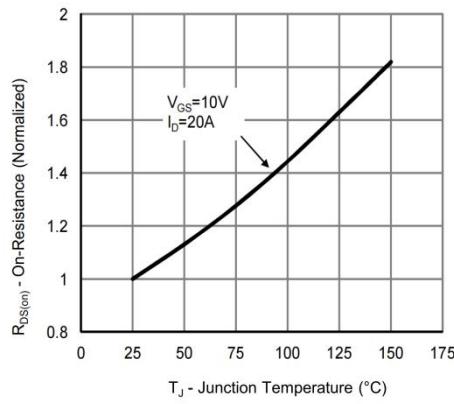
**Transfer Characteristics**



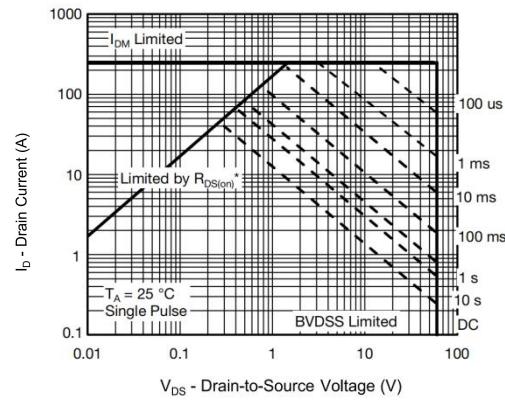
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

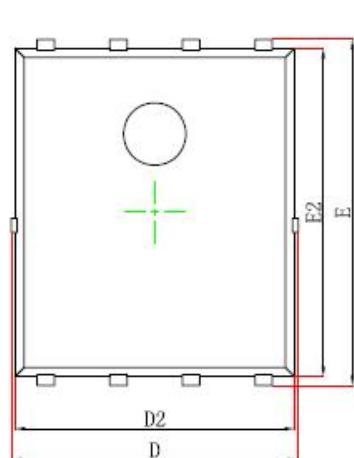


**On-Resistance vs. Junction Temperature**

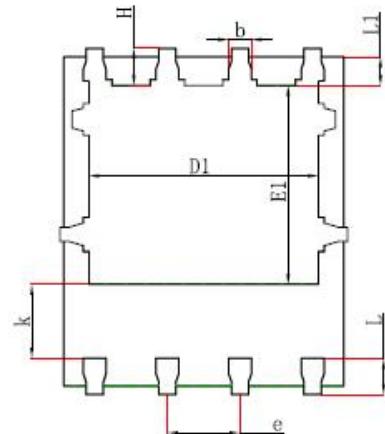


**Safe Operating Area, Junction-to-Ambient**

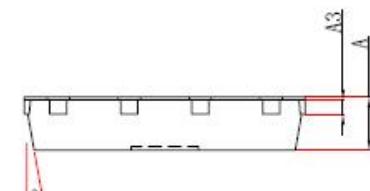
➤ Package Information



Top View  
[顶视图]



Bottom View  
[底视图]

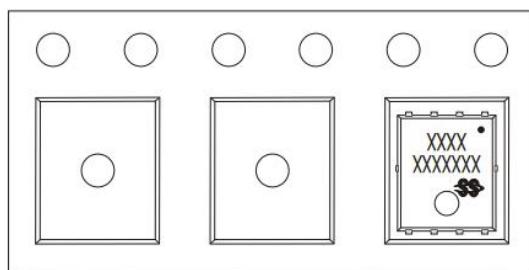
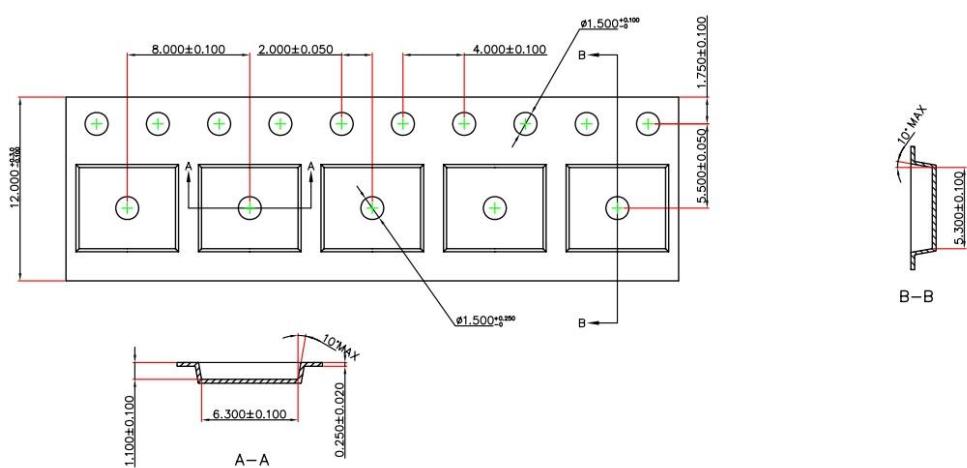
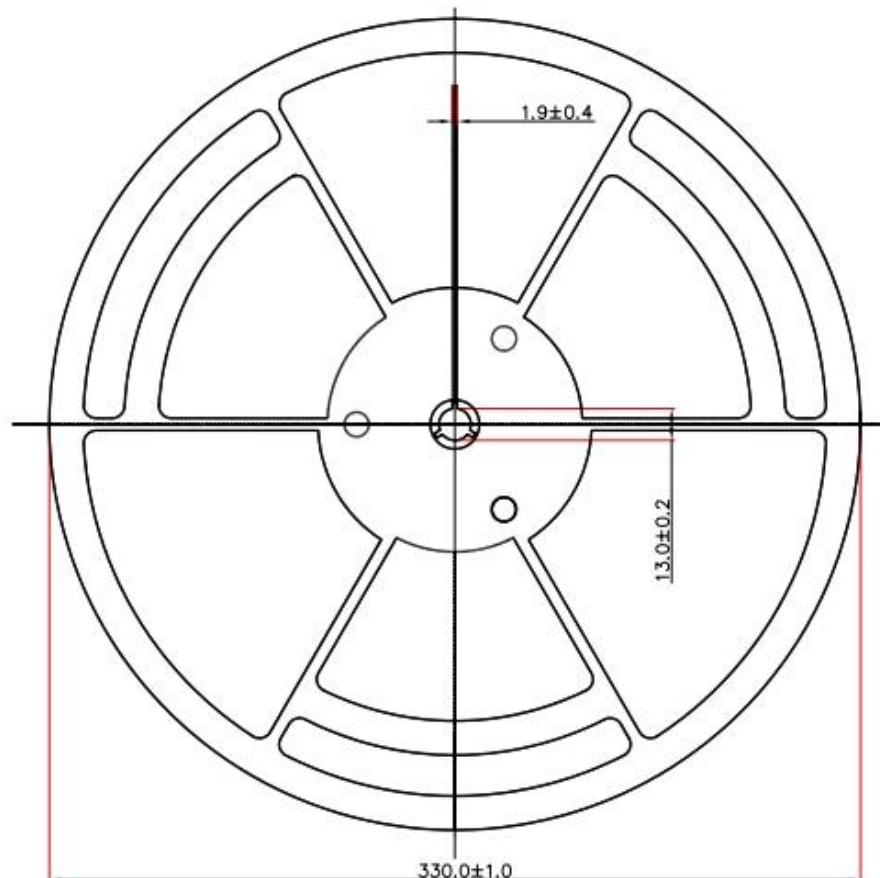


Side View  
[侧视图]

Package: PDNF5X6-8L

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF		0.010REF	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP		0.050TYP	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
$\theta$	10°	12°	10°	12°

## ➤ Tape and Reel





**SSC8L62GN6**

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